

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0110K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

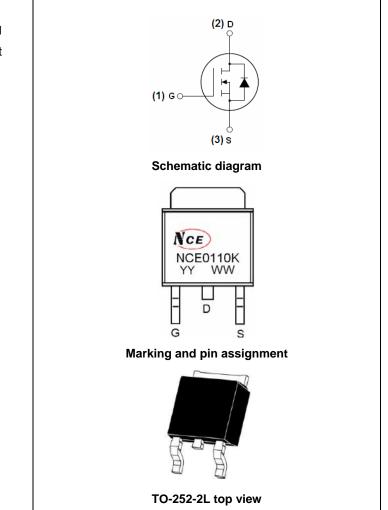
- V_{DS} =100V,I_D =9.6A
 - $R_{DS(ON)} < 140 m\Omega @ V_{GS}=10V$ (Typ:108m Ω)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE0110K	NCE0110K	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_c=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	100	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	Ι _D	9.6	А
Drain Current-Continuous(T _C =100°C)	I _D (100℃)	6.5	А
Pulsed Drain Current	I _{DM}	58	А
Maximum Power Dissipation	PD	30	W
Derating factor		0.2	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	150	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	°C





Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	R _{θJC}	5	°C/W
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Electrical Characteristics (T_c=25[°]C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics	·						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA 100		110	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)	·						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.2	1.8	2.5	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =6A	-	108	140	mΩ	
Forward Transconductance	g fs	V _{DS} =25V,I _D =6A	3.5	-	-	S	
Dynamic Characteristics (Note4)			•				
Input Capacitance	C _{lss}		-	690	-	PF	
Output Capacitance	C _{oss}	$V_{DS}=25V, V_{GS}=0V,$	-	120	-	PF	
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	90	-	PF	
Switching Characteristics (Note 4)						•	
Turn-on Delay Time	t _{d(on)}		-	11	-	nS	
Turn-on Rise Time	tr	V _{DD} =30V,I _D =2A,R _L =15Ω	-	7.4	-	nS	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =2.5Ω	-	35	-	nS	
Turn-Off Fall Time	t _f		-	9.1	-	nS	
Total Gate Charge	Qg	V/ 20V/L 2A	-	15.5		nC	
Gate-Source Charge	Q _{gs}	V_{DS} =30V,I _D =3A,	-	3.2	-	nC	
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	4.7	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =9.6A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	9.6	A	
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =9.6A	-	21		nS	
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	97		nC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				y LS+LD)	
				- 1.2 V - 9.6 A 21 ni 97 ni			

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t $\,\leq\,$ 10 sec.
- 3. Pulse Test: Pulse Width $\,\leqslant\,$ 300 μ s, Duty Cycle $\,\leqslant\,$ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^\circ \!\! \mathrm{C}$,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25\Omega

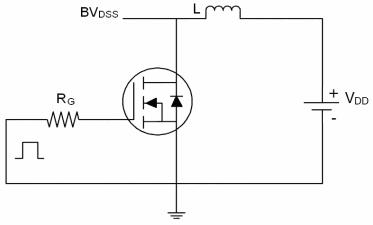


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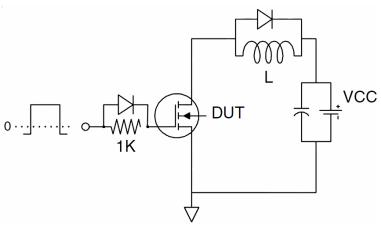
Pb Free Product



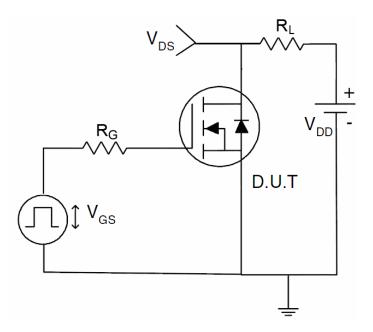
Test Circuit 1) E_{AS} test Circuit



2) Gate charge test Circuit



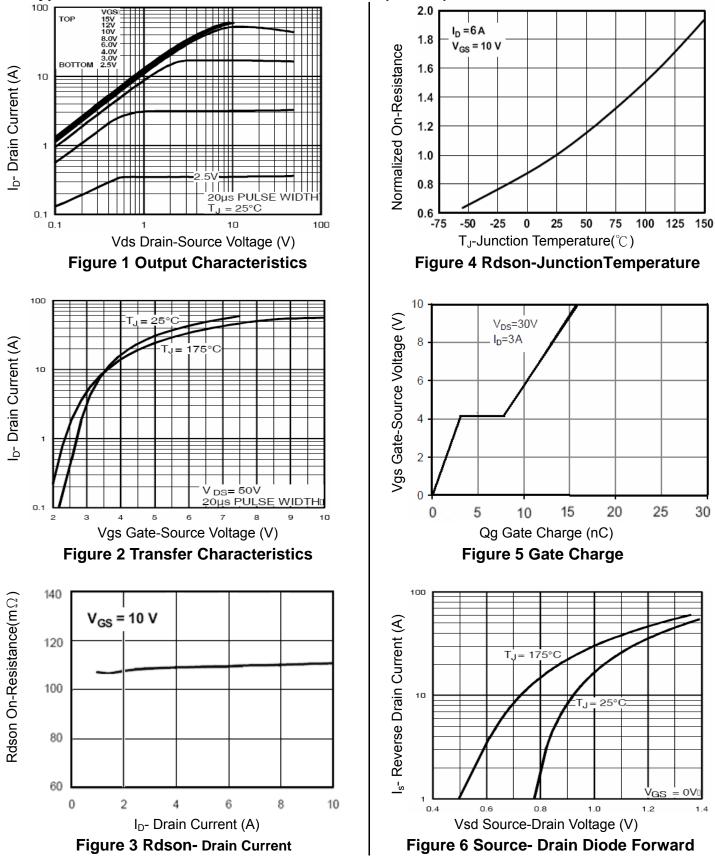
3) Switch Time Test Circuit







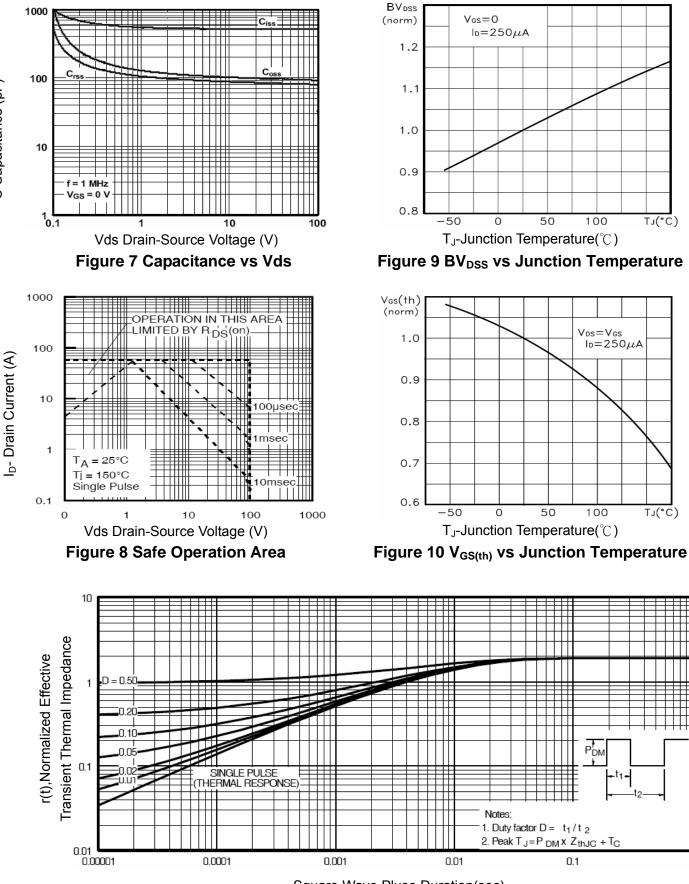
Typical Electrical and Thermal Characteristics (Curves)

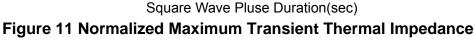




C Capacitance (pF)

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NCE0110K

TJ(°C)

TJ(°C)

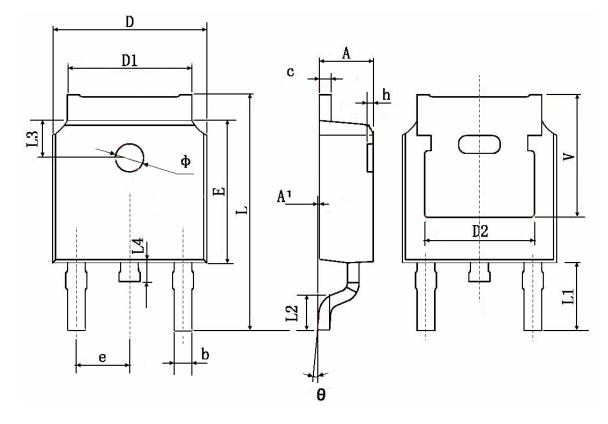


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NCE0110K

TO-252 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	B TYP.	0.190	TYP.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063	03 TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350) TYP.	0.211	TYP.	







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